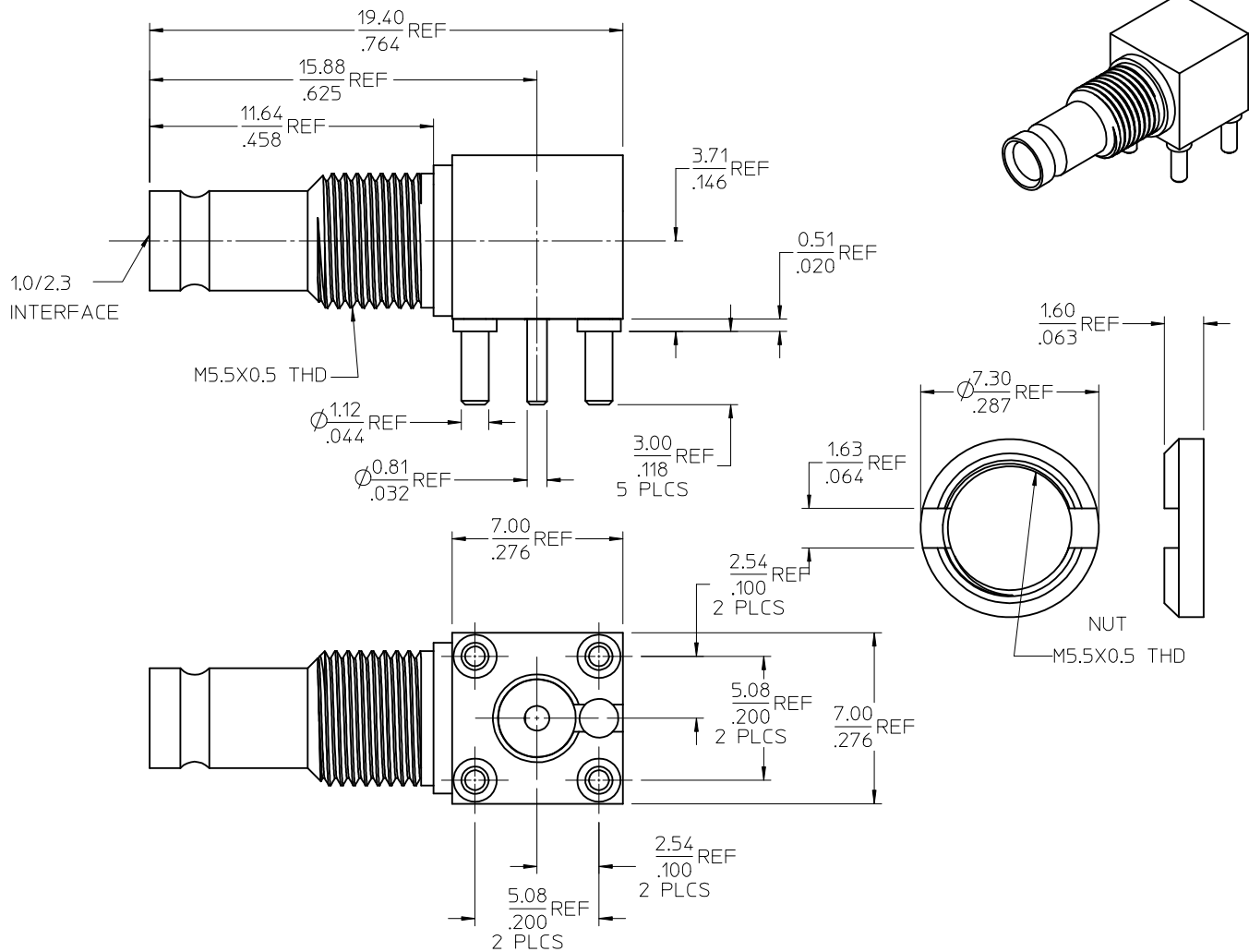


MATERIALS AND FINISHES

BODY, PIN, RETAINING RING, NUT: BRASS  
PLATED: SEE TABLE

CONTACT: PHOSPHOR BRONZE  
PLATED: GOLD

INSULATOR: TEFLON



PS-89675-3450	PRODUCT SPECIFICATION
CECC 22 230	INTERFACE
SPECIFICATION	DESCRIPTION

73174-0411	GOLD
73174-0410	NICKEL
PART NO.	PLATING

UNLESS OTHERWISE SPECIFIED DIMS ARE MILLIMETERS AND ANGLES ARE DEGREES.

- ALL OVER.
- NO CHATTER OR NON-UNIFORM SURFACE FINISH ALLOWED.
- PARTS TO BE FREE OF BURRS & SHARP EDGES 0.13(0.005) MAX BREAK.
- EXTERNAL THREADS TO BE ROLLED OR SINGLE POINT.
- DIAMETERS TO BE CONCENTRIC WITHIN 0.08(0.003) TIR.

CHG: PCB CENTER HOLE WAS Ø.051 REMOVED PLATING THICKNESS

EC NO: URF2009-0277  
2008/11/24  
DRAWN: WIENER  
2008/11/24  
CHKD: SHAH  
2008/11/24  
APPR: WIENER

QUALITY SYMBOLS  
▽=0  
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES ±	±
3 PLACES ±	±
2 PLACES ±	±
1 PLACE ±	±
ANGULAR ± 2 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM/IN	
DRAWN BY	DATE
SSS	2004/03/02
CHECKED BY	DATE
TEF	2004/03/02
APPROVED BY	DATE
GMH	2004/03/02
MATERIAL NO.	DOCUMENT NO.
SEE TABLE	SD-73174-041

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	METRIC	
1.0/2.3 JACK, R/A PCB 50 OHMS, EWR-2361 1.0/2.3-J/PCB		
MOLEX INCORPORATED		SHEET NO.
		1 OF 1
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